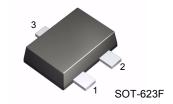


## **FJZ594J**

## **Capacitor Microphone Applications**

- Especially Suited for use in Audio, Telephone Capacitor Microphones
- Excellent Voltage Characteristic
- · Excellent Transient Characteristic



1. Drain 2. Source 3. Gate

## Si N-channel Junction FET

## Absolute Maximum Ratings Ta=25°C unless otherwise noted

Symbol	Parameter	Ratings	Units
$V_{GDO}$	Gate-Drain Voltage	-20	V
I <sub>G</sub>	Gate Current	10	mA
I <sub>D</sub>	Drain Current	1	mA
$P_{D}$	Power Dissipation	100	mW
T <sub>J</sub>	Junction Temperature	150	°C
T <sub>STG</sub>	Storage Temperature	-55 ~ 150	°C

## **Electrical Characteristics** $T_a$ =25°C unless otherwise noted

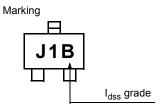
Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
$BV_{GDO}$	Gate-Drain Breakdown Voltage	I <sub>G</sub> = -100uA	-20			V
V <sub>GS</sub> (off)	Gate-Source Cut-off Voltage	V <sub>DS</sub> =5V, I <sub>D</sub> =1μA		-0.6	-1.5	V
I <sub>DSS</sub>	Drain Current	V <sub>DS</sub> =5V, V <sub>GS</sub> =0	150		350	μΑ
ly <sub>fs</sub> l	Forward Transfer Admittance	V <sub>DS</sub> =5V, V <sub>GS</sub> =0, f=1MHz	0.4	1.2		mS
C <sub>ISS</sub>	Input Capacitance	V <sub>DS</sub> =5V, V <sub>GS</sub> =0, f=1MHz		3.5		pF
C <sub>RSS</sub>	Output Capacitance	V <sub>DS</sub> =5V, V <sub>GS</sub> =0, f=1MHz		0.65		pF

## Thermal Characteristics $T_C=25$ °C unless otherwise noted

Symbol	Parameter	Max	Units
$R_{\theta jA}$	Thermal Resistance, Junction to Ambient	1250	°C/W

# I<sub>DSS</sub> Classification

Classification	В	С
I <sub>DSS</sub> (μA)	150 ~ 240	210 ~ 350



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# **Typical Characteristics**

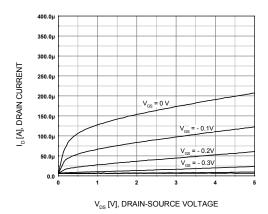


Figure 1. Static Characteristics

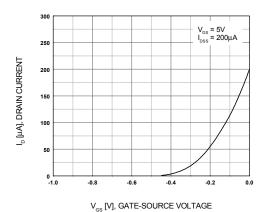


Figure 2. Transfer Characteristic

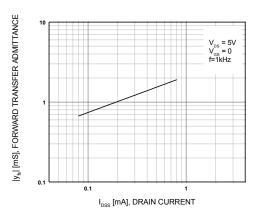


Figure 3. Forward Transfer Admittance

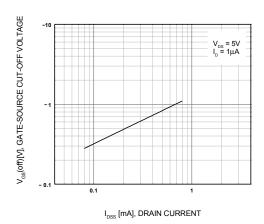


Figure 4. Cut-Off Voltage

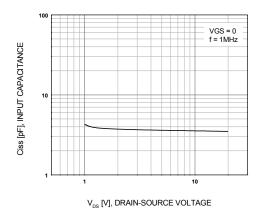


Figure 5. Input Capacitance

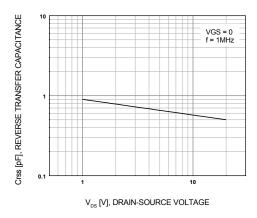


Figure 6. Reverse Transfer Capacitance

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# Typical Characteristics (Continued)

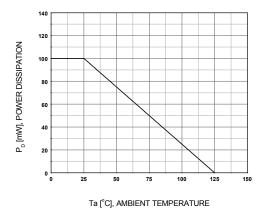
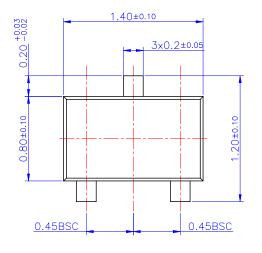


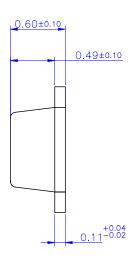
Figure 7. Power Derating

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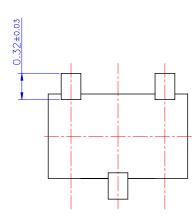
# **Package Dimensions**

# SOT-623F









Dimensions in Millimeters

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Bottomless™	FAST <sup>®</sup>	LittleFET™	Power247™	SuperSOT™-3
CoolFET™	FASTr™	MicroFET™	PowerTrench®	SuperSOT™-6
$CROSSVOLT^{\text{TM}}$	FRFET™	MicroPak™	QFET <sup>®</sup>	SuperSOT™-8
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E <sup>2</sup> CMOS™	HiSeC™	MSXPro™	Quiet Series™	TruTranslation™
EnSigna™	I <sup>2</sup> C <sup>TM</sup>	OCX™	RapidConfigure™	UHC™
Across the board.	. Around the world.™	OCXPro™	RapidConnect™	UltraFET <sup>®</sup>
The Power Franc	hise™	OPTOLOGIC <sup>®</sup>	SILENT SWITCHER®	VCX™
Programmable Ad	ctive Droop™	OPTOPLANAR™	SMART START™	

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